

IR-2548 DIV (2-3610)

FIVE LAYER ADHESIVE/INSULATOR/METAL/ INSULATOR/ADHESIVE
TAPE FOR SEMICONDUCTOR DIE PACKAGING

ABSTRACT OF THE DISCLOSURE

A novel five-layer tape is provided for applications such as bonding, interconnection and insulation of different parts of a semiconductor package at the same time. The five layer tape includes a metal conductive layer that is sandwiched between two insulative layers, that are themselves in turn sandwiched by two adhesive layers. Windows cut into the insulative and adhesive layers on either the top or bottom of the tape permit electrical connection to the metallic conductive layer. The tape may be made from two insulation sheets that have an adhesive layer and a metallic interconnect. In turn, the tape enables the manufacturer to overcome physical limitations in forming conduction paths, including permitting the connection of multiple die where the terminals of the one die are obscured by the other die.